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N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)}	I _D T _A = +25°C
001/	25mΩ @ V _{GS} = 10V	6.2A
30V	$28m\Omega$ @ $V_{GS} = 4.5V$	5.8A

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance $(R_{DS(ON)})$ and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Load Switch
- DC-DC Converters
- Power Management Functions

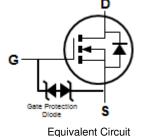
Mechanical Data

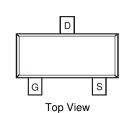
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram (3)
- Weight: 0.009 grams (Approximate)





SOT23





Top View

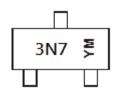
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN3023L-7	SOT23	3,000/Tape & Reel
DMN3023L-13	SOT23	10,000/Tape & Reel

Notes:

- $1.\ No\ purposely\ added\ lead.\ Fully\ EU\ Directive\ 2002/95/EC\ (RoHS)\ \&\ 2011/65/EU\ (RoHS\ 2)\ compliant.$
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



3N7 = Product Type Marking Code Y or \overline{Y} = Year (ex: B = 2014) M = Month (ex: 9 = September)

Date Code Key

Year	2014	2015	2016	2017	⁷ 201	8 20)19	2020	2021	2022	2023	2024
Code	В	С	D	Е	F	(G	Н		J	K	L
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	30	V		
Gate-Source Voltage	V_{GSS}	±20	V		
Continuous Drain Current (Note 6) V _{GS} = 10V	I _D	6.2 4.9	Α		
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%)	I _{DM}	44	Α		
Maximum Body Diode Forward Current (Note 6)	Is	1.5	Α		
Avalanche Current (Note 7) L = 0.1mH			I _{AS}	17.5	Α
Avalanche Energy (Note 7) L = 0.1mH			Eas	15.2	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Units		
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	В	0.9	W	
Total Power Dissipation (Note 3)	$T_A = +70$ °C	P_{D}	0.6		
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	В	144	°C/W	
Thermal hesistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	103	C/VV	
Total Bower Dissipation (Note 6)	$T_A = +25^{\circ}C$	ь	1.3	W	
Total Power Dissipation (Note 6)	$T_A = +70$ °C	P_{D}	0.8		
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	В	97		
memai nesistance, Junction to Ambient (Note 6)		$R_{\theta JA}$	70	°C/W	
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	24			
Operating and Storage Temperature Range	•	$T_{J_1}T_{STG}$	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

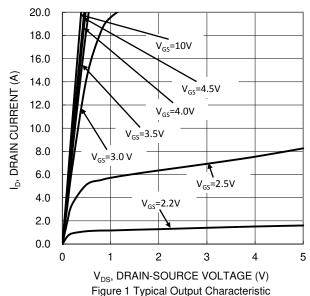
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}		_	1	μΑ	$V_{DS} = 24V, V_{GS} = 0V$	
Gate-Body Leakage	I _{GSS}	_	_	±10	μΑ	$V_{GS}=\pm 16V,\ V_{DS}=0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	0.8		1.8	V	$V_{DS}=V_{GS},I_D=250\mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}		_	25 28 68	mΩ	$V_{GS} = 10V$, $I_D = 4.0A$ $V_{GS} = 4.5V$, $I_D = 3.5A$ $V_{GS} = 2.5V$, $I_D = 2.5A$	
Source-Drain Diode Forward Voltage	V_{SD}	_	_	1.2	V	$V_{GS} = 0V$, $I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}		873	_	pF		
Output Capacitance	Coss		121	_	pF	$V_{DS} = 15V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}		67	_	pF	1 - 1.5111112	
Gate Resistance	R_g	1	77	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 10V)	Q_g		18.4	_	nC		
Total Gate Charge (V _{GS} = 4.5V)	Qg		8.3	_	nC	V _{DS} = 15V, I _D = 4A	
Gate-Source Charge	Q_{gs}		2.2	_	nC	VDS = 13V, ID = 4A	
Gate-Drain Charge	Q_{gd}		2.5	_	nC		
Turn-On Delay Time	t _{D(ON)}		17	_	ns		
Turn-On Rise Time	t _R		18	_	ns	$V_{DD} = 15V, V_{GS} = 10V,$	
Turn-Off Delay Time	t _{D(OFF)}		231	_	ns	$R_L = 15\Omega, R_G = 6\Omega$	
Turn-Off Fall Time	t _F		70		ns		

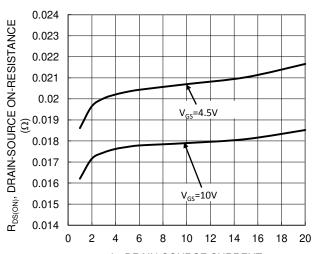
 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

9. Guaranteed by design. Not subject to product testing.

^{7.} I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep $T_{J} = +25^{\circ}C$. 8. Short duration pulse test used to minimize self-heating effect.







I_D, DRAIN-SOURCE CURRENT Figure 3 Typical On-Resistance vs Drain Current and Gate Voltage

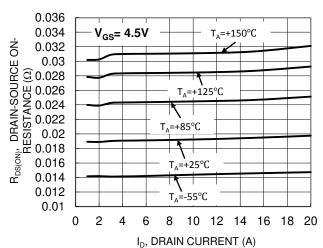


Figure 5 Typical On-Resistance vs Drain Current and Temperature

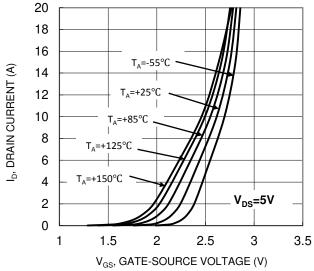


Figure 2 Typical Transfer Characteristic

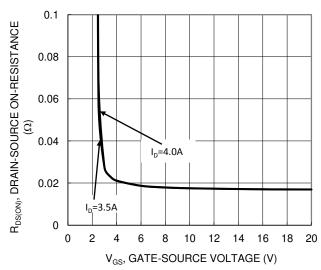


Figure 4 Typical Transfer Characteristic

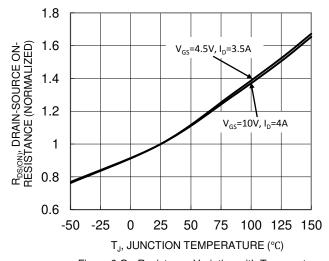


Figure 6 On-Resistance Variation with Temperature



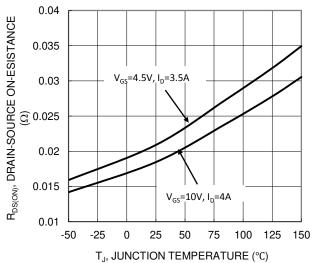
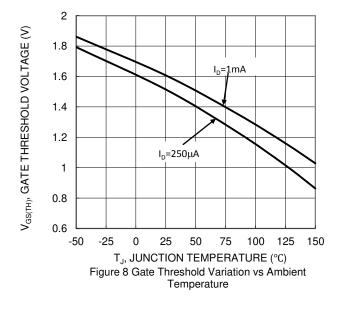


Figure 7 On-Resistance Variation with Temperature



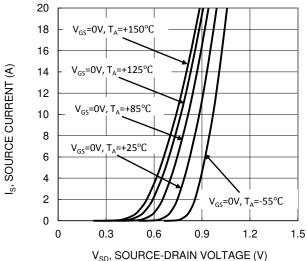
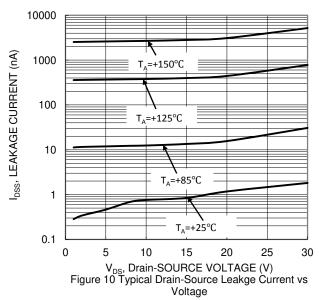
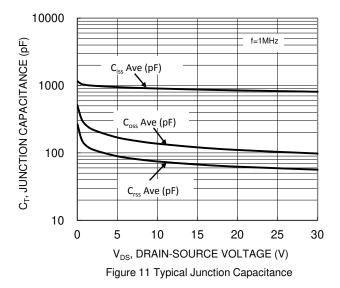
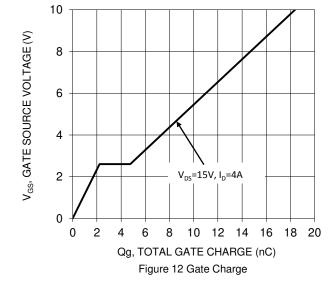


Figure 9 Diode Forward Voltage vs. Current









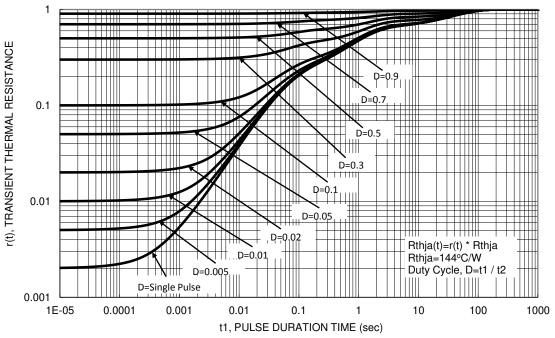
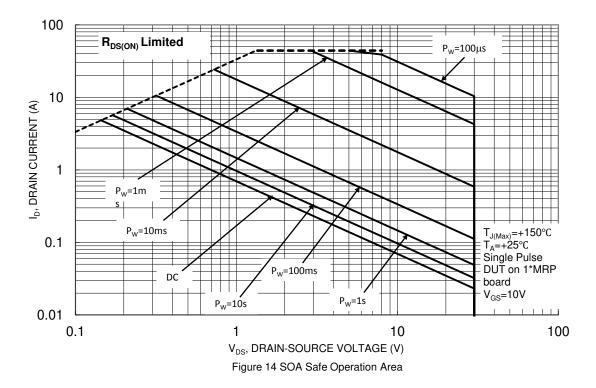


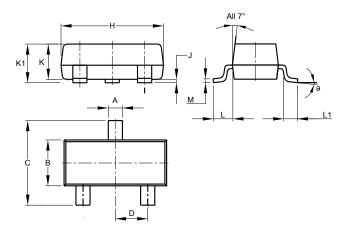
Figure 13 Transient Thermal Resistance





Package Outline Dimensions

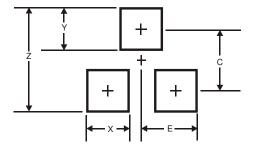
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT23						
Dim	Min	Max	Тур			
Α	0.37	0.51	0.40			
В	1.20	1.40	1.30			
С	2.30	2.50	2.40			
D	0.89	1.03	0.915			
F	0.45	0.60	0.535			
G	1.78	2.05	1.83			
H	2.80	3.00	2.90			
J	0.013	0.10	0.05			
K	0.890	1.00	0.975			
K1	0.903	1.10	1.025			
L	0.45	0.61	0.55			
L1	0.25	0.55	0.40			
М	0.085	0.150	0.110			
а	8°					
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35



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